

**Amendments to the Specification:**

Please replace three paragraphs beginning at page 4, line 21, with the following amended paragraphs:

~~In~~ Also, provided is (2) the cooling device for an electronic component according to Item (1) above, wherein the thermoelectric conversion material is either a p-type material or an n-type material or a combination of p-type and n-type materials arranged alternately in series.

The present invention further provides (3) a cooling system including two or more stacked cooling devices according to Item (1) [[or (2)]] above.

The present invention further provides (4) a cooling system including the cooling device according to Item (1) [[or (2)]] above.